

Name: Solutions

**EE 40**

**FINAL EXAM**

**December 13, 2002**

**PLEASE WRITE YOUR NAME ON EACH ATTACHED PAGE**

**PLEASE SHOW YOUR WORK TO RECEIVE PARTIAL CREDIT**

Problem 1: 10 Points Possible \_\_\_\_\_

Problem 2: 10 Points Possible \_\_\_\_\_

Problem 3: 15 Points Possible \_\_\_\_\_

Problem 4: 15 Points Possible \_\_\_\_\_

Problem 5: 30 Points Possible \_\_\_\_\_

Problem 6: 30 Points Possible \_\_\_\_\_

Problem 7: 60 Points Possible \_\_\_\_\_

Part 7a: 30 Points Possible \_\_\_\_\_

Part 7b: 30 Points Possible \_\_\_\_\_

Part 7c: 30 Points Possible \_\_\_\_\_

Complete 2 of these 3 parts of Problem 7, for a total of 60 points.

If you complete all 3 parts, your 2 highest-scoring parts will count.

Problem 8: 30 Points Possible \_\_\_\_\_

Problem 9: 1 Point Possible \_\_\_\_\_

**TOTAL: 201 Points Possible \_\_\_\_\_**

Name: Solutions

**Problem 1: 10 Points Possible**

Match each description below to a substance by writing the number next to the substance.

Note: Some substances have more than one matching description!

1. Makes a good material for transistor gate because of its low resistance and ability to withstand high temperature anneals
2. Deposited onto wafer by "sputtering"
3. Implanted into wafer by high-energy ion impact and heated to a temperature  $> 800\text{ }^{\circ}\text{C}$
4. "Grown" on wafer through thermal oxidation
5. Medium which allows designer to pattern layers using a mask
6. Protects materials from removal during "etching"
7. Serves as insulator between conducting layers
8. Deposited by shooting argon atoms at a target made of the deposit material, knocking loose atoms which fall on the wafer surface
9. Parts which are exposed to light wash away in a developing liquid
10. Deposition of this material causes damage to wafer, requiring "annealing" to repair

Silicon Dioxide 4, 7

Dopants 3, 10

Aluminum 2, 8

Photoresist 5, 6, 9

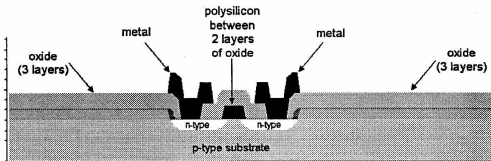
Polysilicon 1

Name: \_\_\_\_\_

**Problem 2:** 10 Points Possible

Consider the NMOS transistor with cross-section shown. Put the steps involved in the fabrication of this device in correct order.

Pattern metal	Step 1: <u>Grow oxide 500 nm</u>
Grow oxide (20 nm thick)	Step 2: <u>Pattern oxide</u>
Implant donors	Step 3: <u>Implant donors</u>
Deposit polysilicon	Step 4: <u>Grow oxide 20 nm</u>
Grow oxide (500 nm thick)	Step 5: <u>Deposit polysilicon</u>
Deposit metal	Step 6: <u>Pattern polysilicon</u>
Pattern polysilicon	Step 7: <u>Deposit oxide 750nm</u>
Pattern oxide	Step 8: <u>Pattern oxide</u>
Deposit oxide (750 nm thick)	Step 9: <u>Deposit metal</u>
Pattern oxide	Step 10: <u>Pattern metal</u>



**Problem 3: 15 Points Possible**

Suppose we have connected the output of CMOS inverter 1 to the input of CMOS inverter 2, where the inverters have the following characteristics:

Both inverters:

$$\mu_N = 500 \text{ cm}^2 / (\text{Vs})$$

$$\mu_P = 250 \text{ cm}^2 / (\text{Vs})$$

$$V_{T(N)} = -V_{T(P)} = 1 \text{ V}$$

$$t_{ox} = 10 \text{ nm (oxide thickness)}$$

$$k_{ox} = 4 \text{ (oxide dielectric constant)}$$

$$V_{DD} = 5 \text{ V}$$

$$L_I = 20 \text{ } \mu\text{m (interconnect length)}$$

$$W_I = 1 \text{ } \mu\text{m (interconnect width)}$$

$$\epsilon_0 = 8.85 \times 10^{-12} \text{ F/m}$$

Inverter 1:

$$L_N = L_P = 2 \text{ } \mu\text{m}$$

$$W_N = 6 \text{ } \mu\text{m}$$

$$W_P = 24 \text{ } \mu\text{m}$$

$$C_{DB(P)} = C_{DB(N)} = 50 \text{ fF}$$

Inverter 2:

$$L_N = L_P = 2 \text{ } \mu\text{m}$$

$$W_N = 8 \text{ } \mu\text{m}$$

$$W_P = 16 \text{ } \mu\text{m}$$

$$C_{DB(P)} = C_{DB(N)} = 75 \text{ fF}$$

Find the propagation delay for the output of inverter 1, when the input of inverter 1 changes from logic 0 to logic 1 instantaneously (after being logic 0 for a long time).

$$t_p = 0.69 \tau$$

$$\tau = R_N (C_{DBN_1} + C_{DBP_1} + C_{GBN_2} + C_{GBP_2} + C_I)$$

$$R_N = 0.75 V_{DD} / I_{DSAT_1} = 0.75 V_{DD} / \left( \frac{W_{N1}}{2L_{N1}} \mu_n C_{ox} (V_{GS1} - V_T)^2 \right)$$

$$= 0.75(5) / \left[ \left( \frac{6 \cdot 10^{-6}}{2 \cdot 2 \cdot 10^{-6}} \right) (500 \cdot 10^{-4}) \left( \frac{4(8.85 \cdot 10^{-12})}{10 \cdot 10^{-9}} \right) (5-1)^2 \right]$$

$$= 883 \Omega$$

$$C_{GBN_2} = C_{ox} W_{N2} L_{N2} = \frac{4(8.85 \cdot 10^{-12})}{10 \cdot 10^{-9}} (8 \cdot 10^{-6})(2 \cdot 10^{-6}) = 56 \text{ fF}$$

$$C_{GBP_2} = C_{ox} W_{P2} L_{P2} = \frac{4(8.85 \cdot 10^{-12})}{10 \cdot 10^{-9}} (16 \cdot 10^{-6})(2 \cdot 10^{-6}) = 112 \text{ fF}$$

$$C_I = C_{ox} W_I L_I = \frac{4(8.85 \cdot 10^{-12})}{10 \cdot 10^{-9}} (1 \cdot 10^{-6})(20 \cdot 10^{-6}) = 70 \text{ fF}$$

$$t_p = 0.69(883)(56 + 112 + 70 + 50 + 50) 10^{-15}$$

$$= \boxed{206 \text{ ps}}$$

**Problem 4: 15 Points Possible**

Suppose I hook an inverter up to one of the inputs of our 3-bit adder's most significant digit function. Find the propagation delay from the input to the output of the inverter when the inverter input A goes from low to high (with the other adder inputs held constant as shown).

For all of the gates, use

$C_{DB(P)} = C_{DB(N)} = 50 \text{ fF}$

$C_{GB(P)} = 50 \text{ fF}$

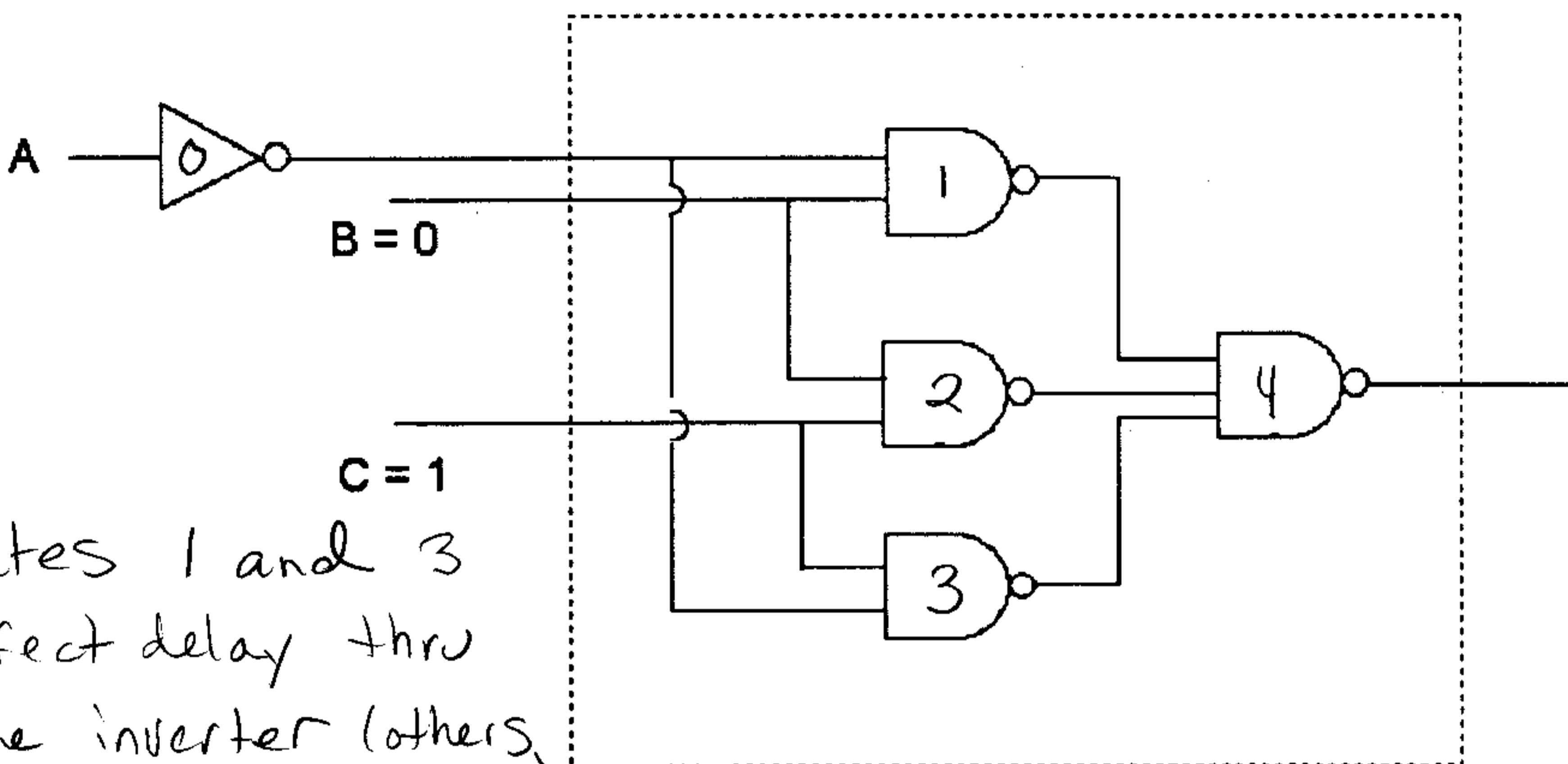
$C_{GB(N)} = 75 \text{ fF}$

$C_I = 100 \text{ fF per gate}$

$R_N = 3 \text{ k}\Omega$

$R_P = 2 \text{ k}\Omega$

A NAND-NAND implementation of the circuit is shown below.



Gates 1 and 3 affect delay thru the inverter (others not directly attached).

One connection to gate 1 and one connection to gate 3: Use 2 gate capacitances ( $C_{GBN}$  and  $C_{GBP}$ ) for gate 1 and for gate 3. Use 2  $C_I$  (2 gates connected).

$$t_p = 0.69 R_N (C_{DBN_0} + C_{DBP_0} + C_{GBN_1} + C_{GBP_1} + C_{GBN_3} + C_{GBP_3} + 2C_I)$$

$$= 0.69 (3000) (50 + 50 + 75 + 50 + 75 + 50 + 2 \cdot 100) 10^{-15}$$

$$= 1.14 \text{ ns}$$

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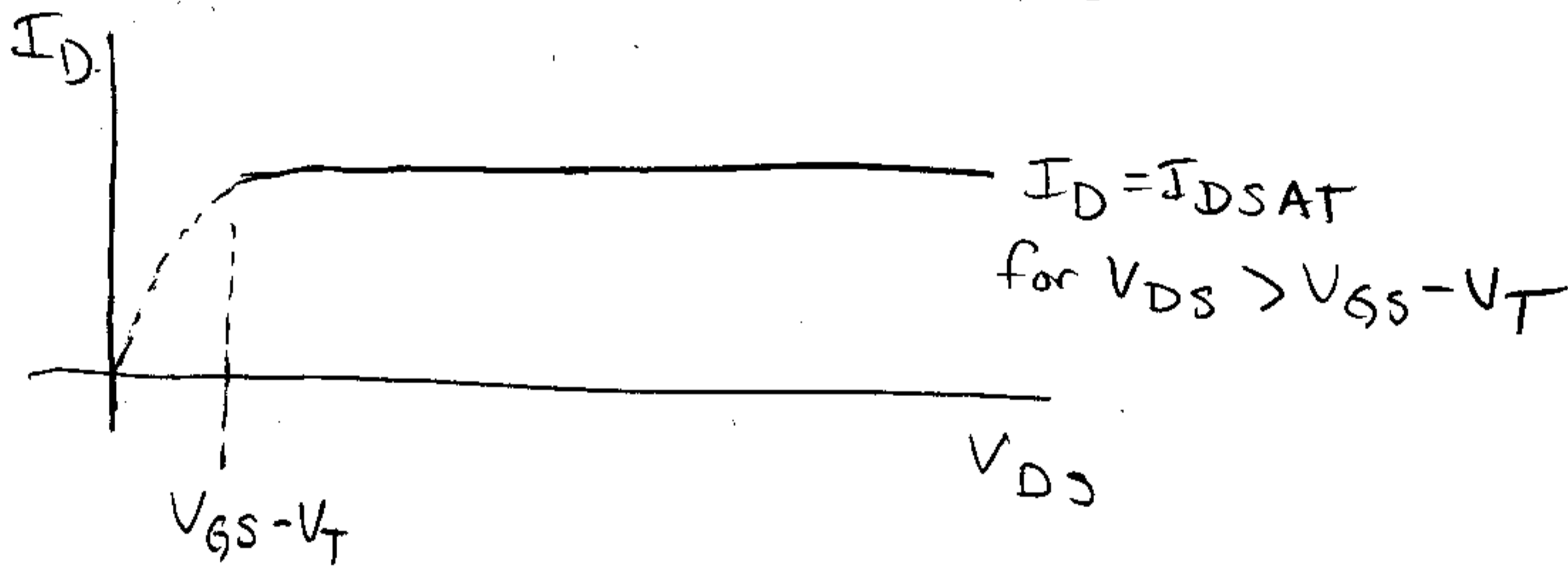
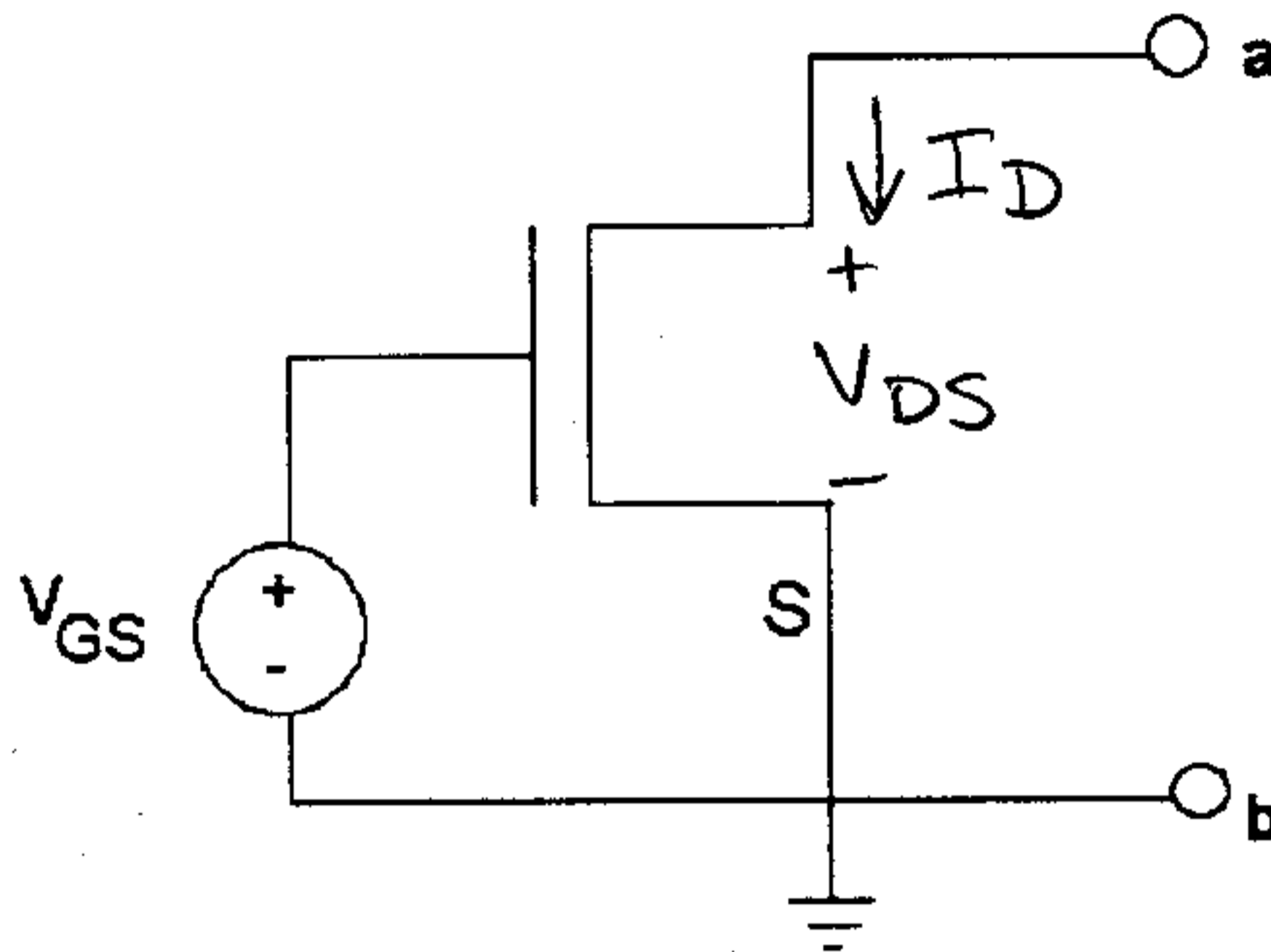
**Problem 5:** 30 Total Points Possible

a) 10 Points Possible

Consider the NMOS transistor circuit below, where  $V_{GS}$  is constant and above  $V_T$ .

Assume  $\lambda = 0$ . Graph the  $I_D$  vs.  $V_{DS}$  relationship for  $V_{DS} > V_{GS} - V_T$ .

Does this circuit have a Thevenin and/or Norton equivalent for this region of operation (when  $V_{DS} > V_{GS} - V_T$ )? If yes, give the equivalents. If no, explain why the equivalents do not exist.

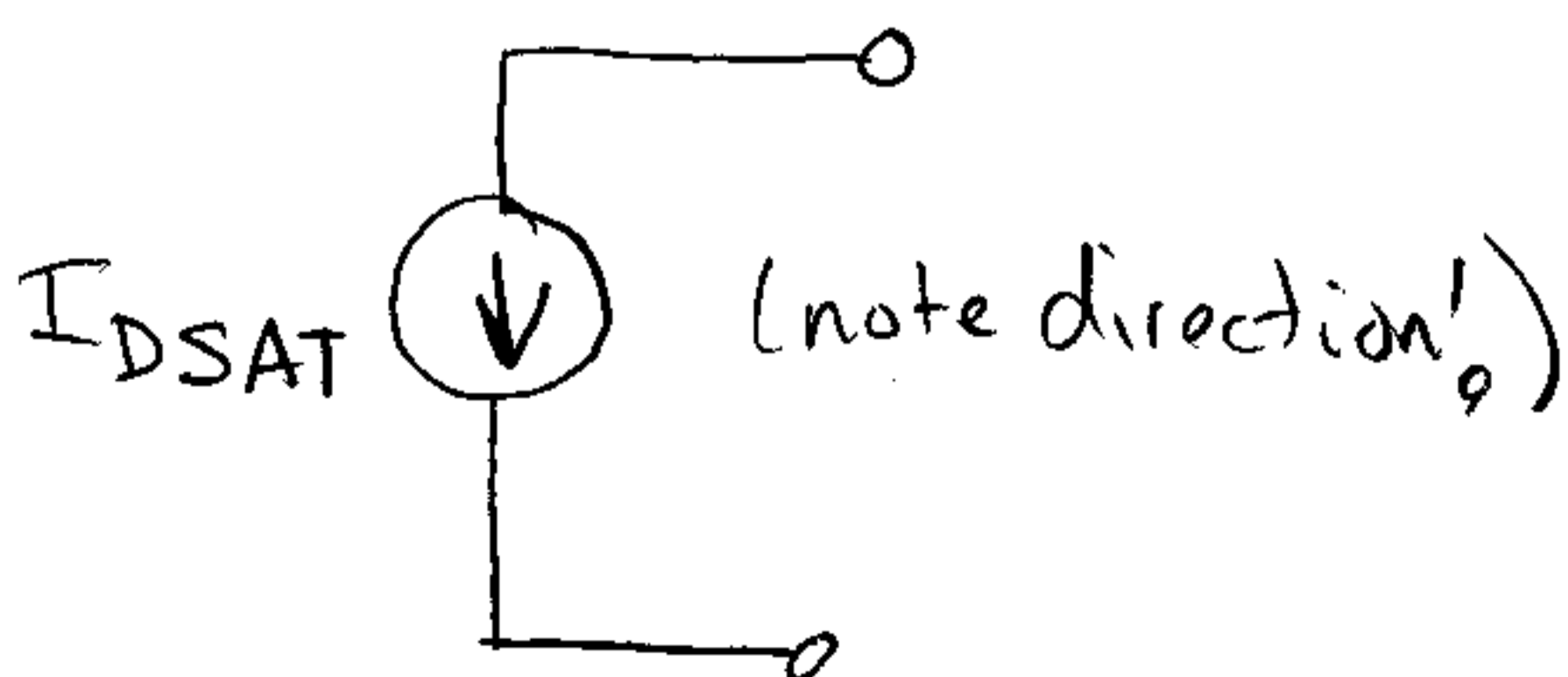


Constant current, any voltage  $\Rightarrow$  current source

Norton equivalent:

Thevenin equivalent:

does not exist for current source



Problem 5 continued

b) 10 Points Possible

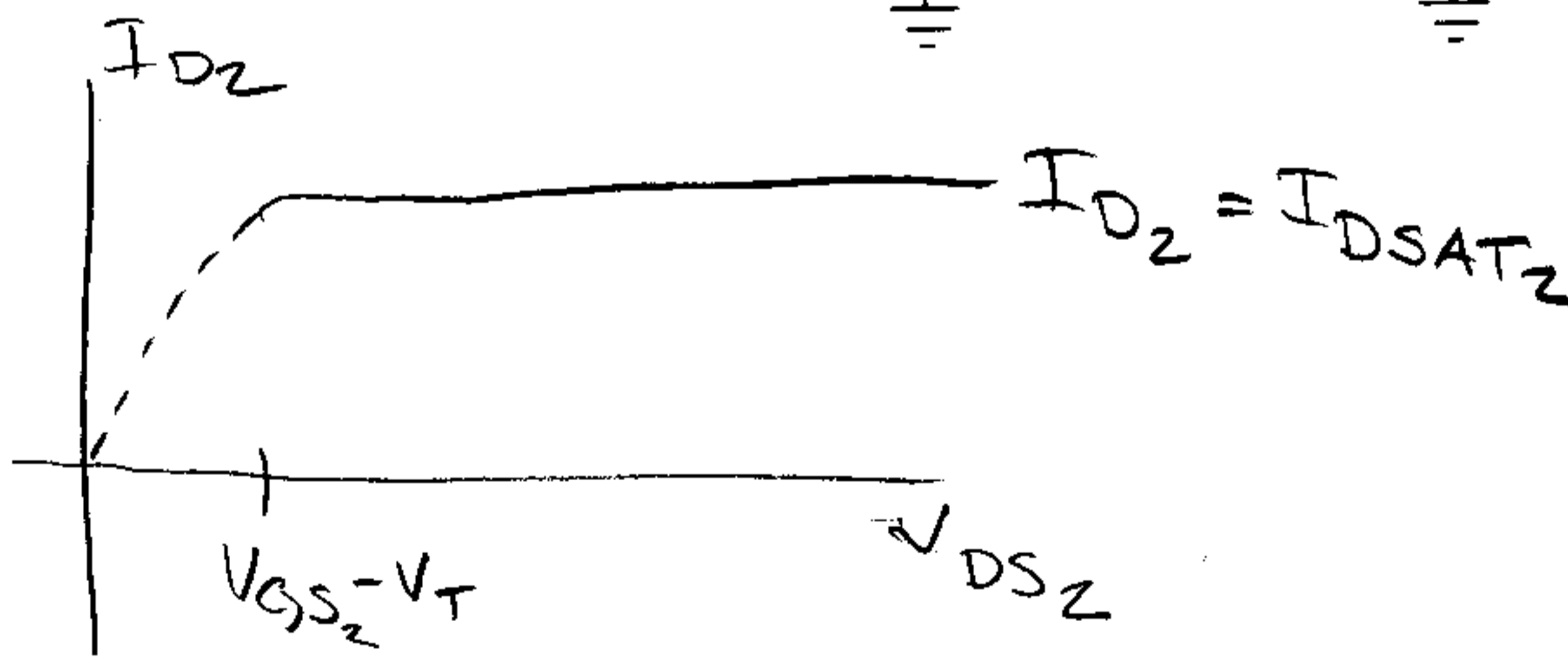
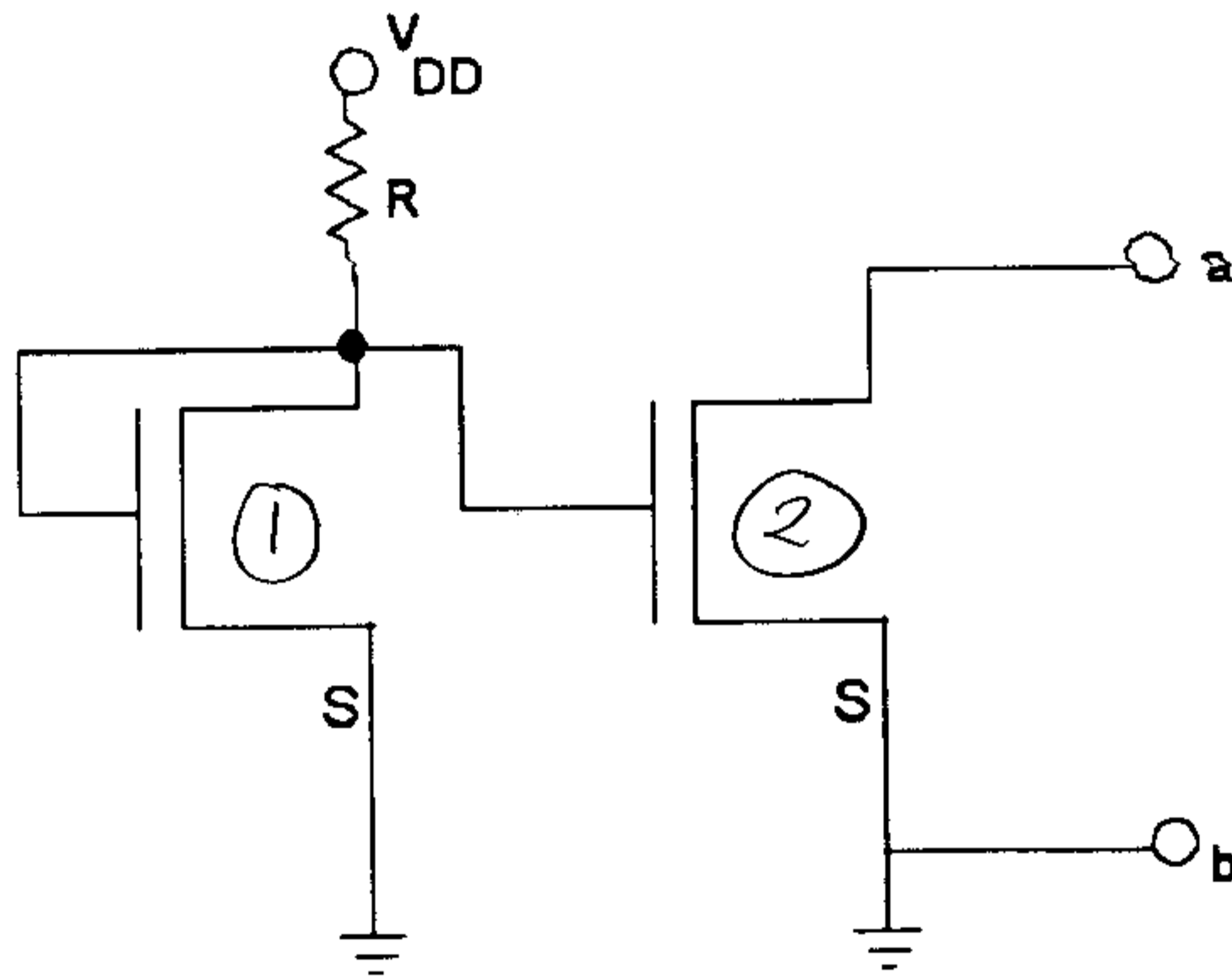
Consider the NMOS transistor circuit below, where  $V_{DD}$  is constant and above  $V_T$ .

Assume that both transistors have all the same parameters, and  $\lambda = 0$ .

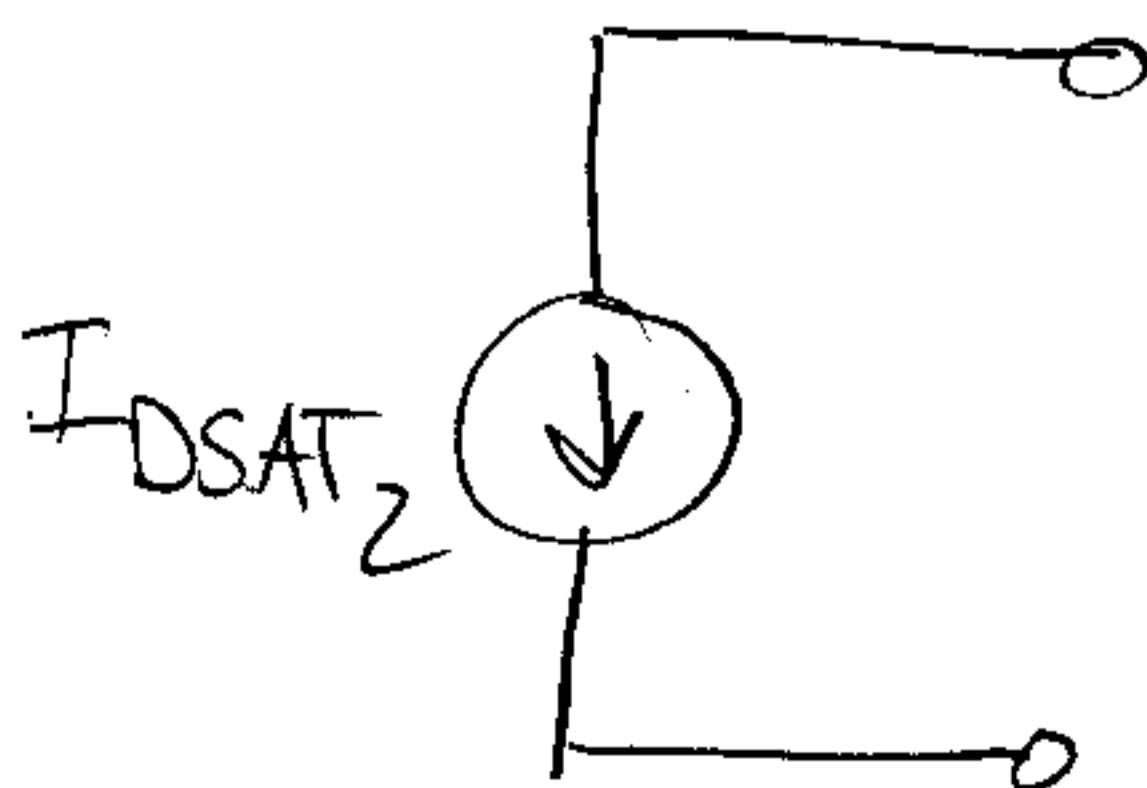
Graph the  $I_{D(2)}$  vs.  $V_{DS(2)}$  relationship for  $V_{DS(2)} > V_{GS(2)} - V_T$ .

Does this circuit have a Thevenin and/or Norton equivalent for this region of operation (when  $V_{DS} > V_{GS} - V_T$ )? If yes, give the equivalents. If no, explain why the equivalents do not exist.

$V_{DS1} = V_{GS2}$   
and is constant  
since supply  
voltage ( $V_{DD}$ )  
is constant.



Norton equivalent:



Thevenin equivalent!  
does not exist  
for current source

Problem 5 continued

c) 10 Points Possible

Suppose that as the circuits operate, they heat up. This causes an increase in the electron mobility  $\mu_n$ . How does this affect the operation of the circuit in Part a? How does this affect the operation of the circuit in Part b?

Part a: When  $\mu_n$  increases,  $I_{DSAT}$  increases.

The current supplied by this "current source" circuit increases.

Part b: When  $\mu_n$  increases, both  $I_{DSAT1}$  and  $I_{DSAT2}$  increase.

An increase in  $I_{DSAT1}$  means that the voltage over the resistor increases.

Since  $R I_{DSAT1} + V_{DS1} = V_{DD}$  (constant),  $V_{DS1}$  must decrease.

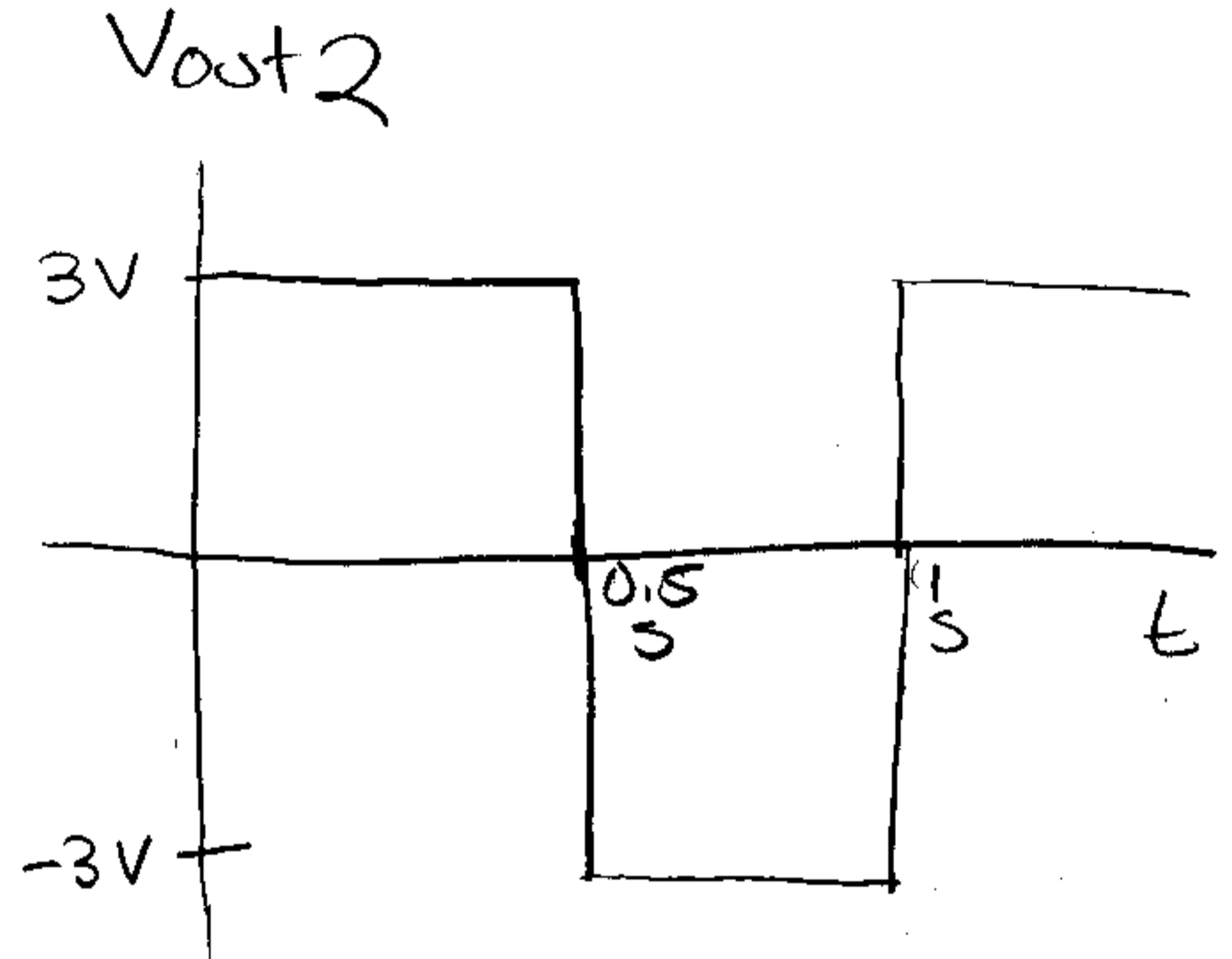
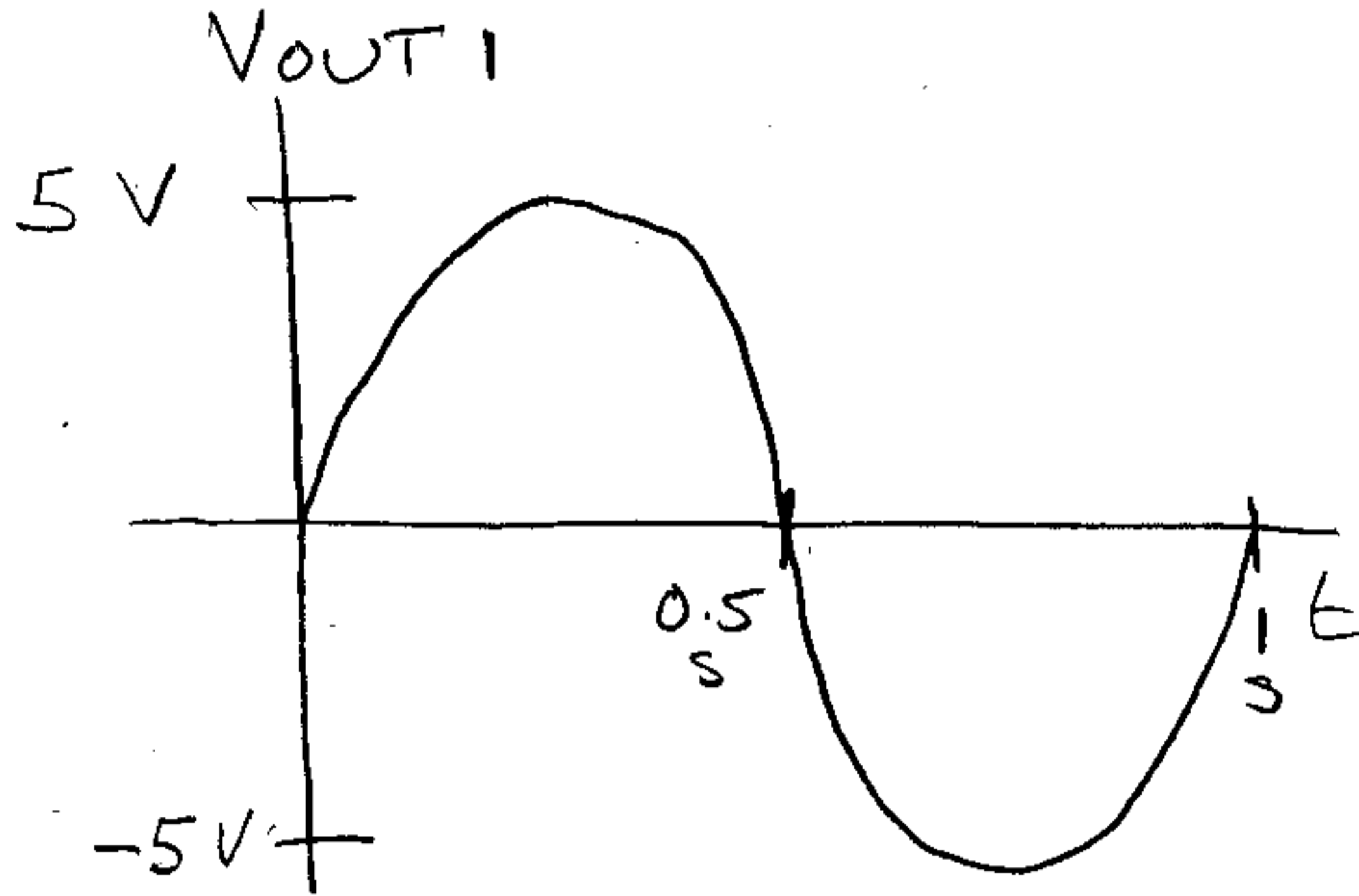
This decreases the value of  $V_{GS2}$  and therefore decreases  $I_{DSAT2}$ .

overall  
The increase in the current supplied by the current source will be smaller <sup>than</sup> <sub>for</sub> <sub>part a</sub> due to this negative feedback.

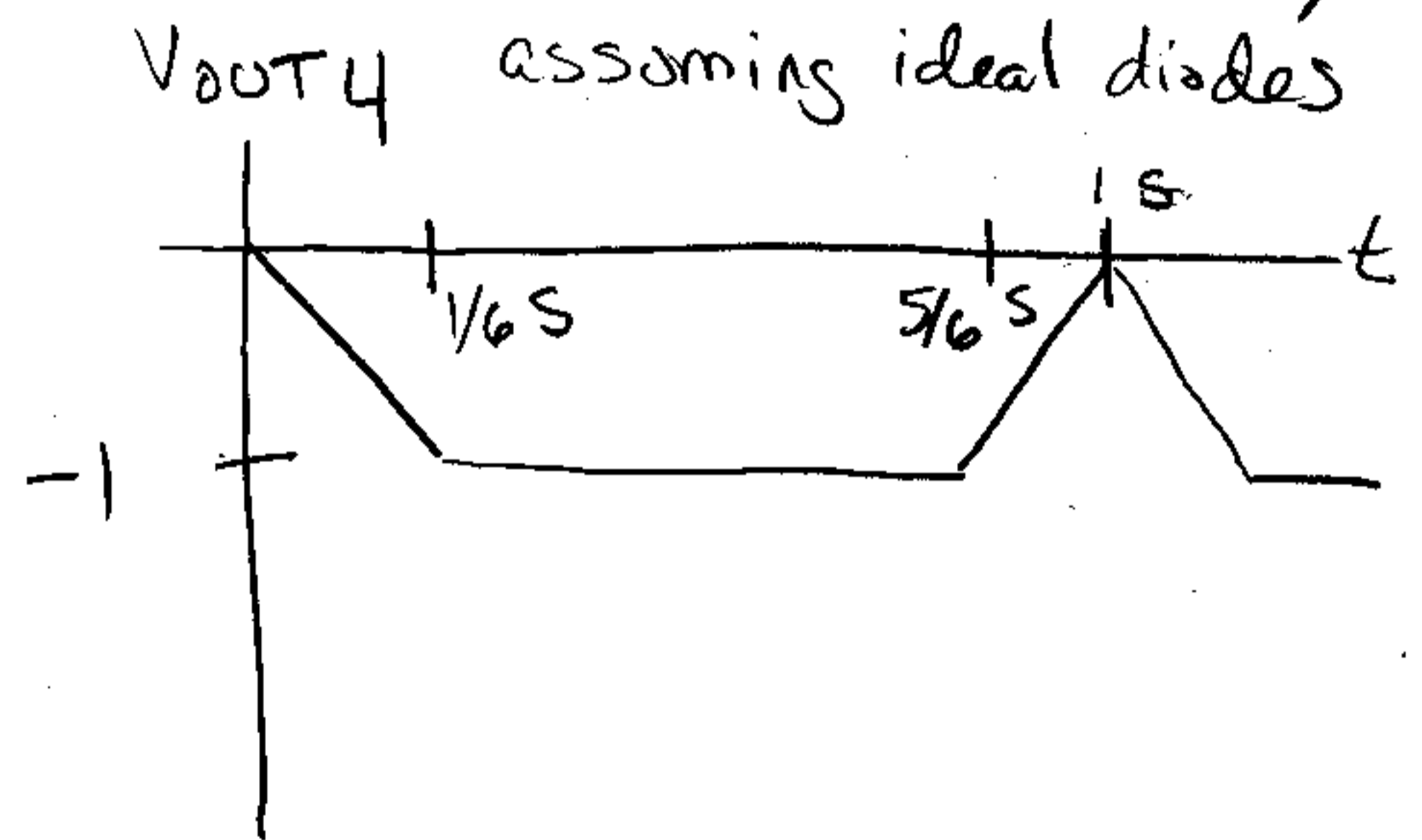
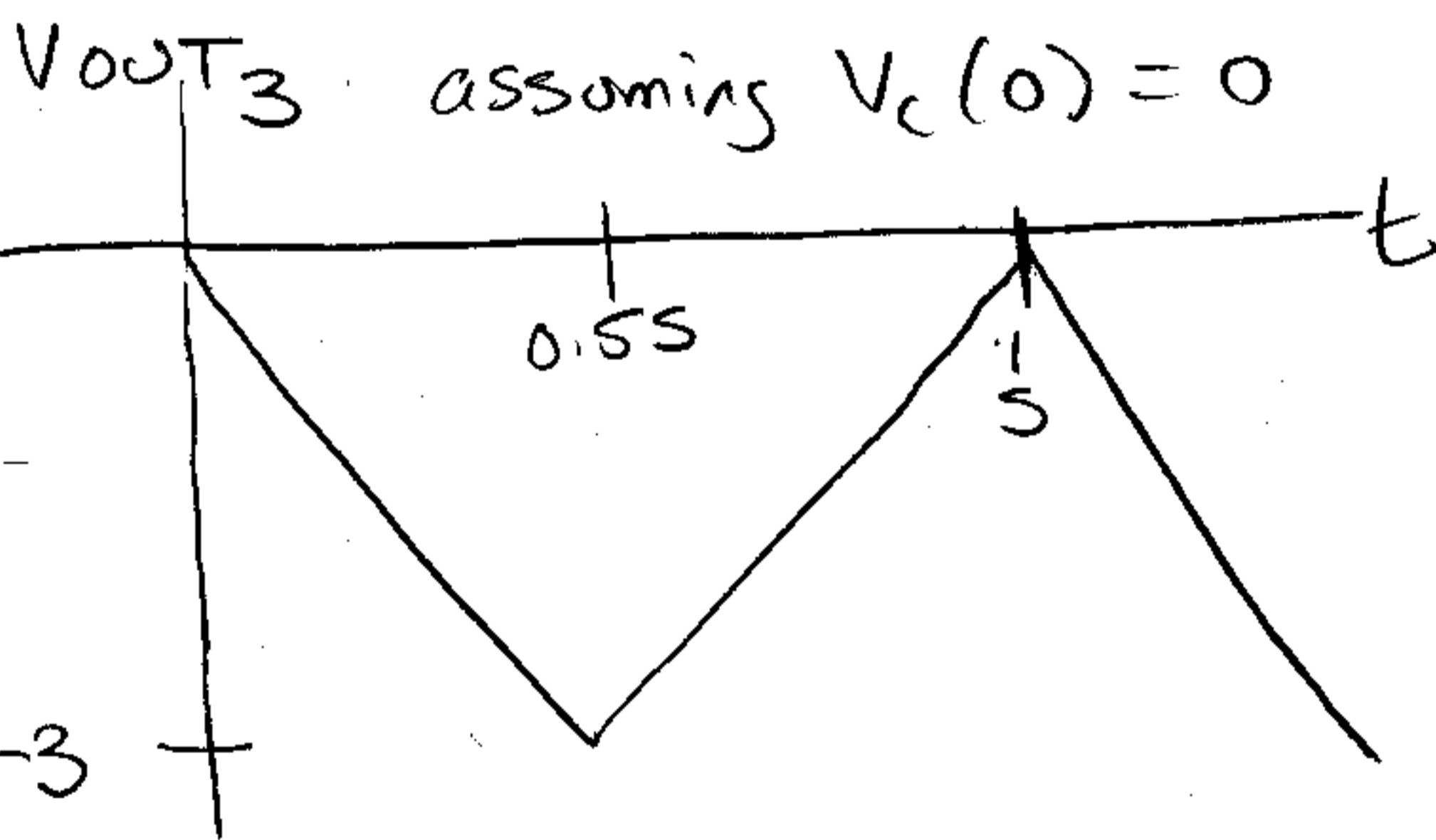


**Problem 6: 30 Points**

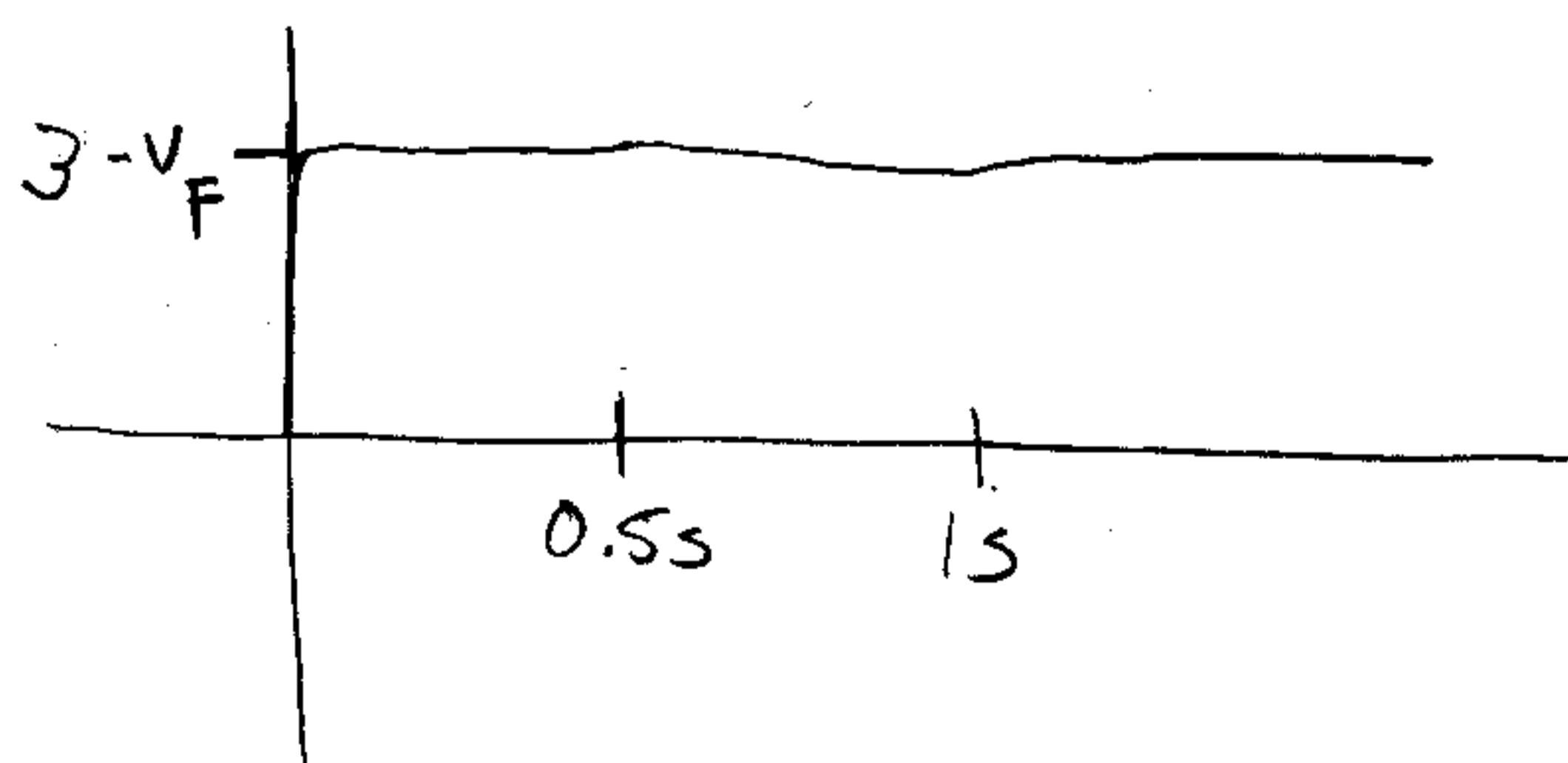
The circuit on the next page has 5 outputs:  $V_{OUT1}$ ,  $V_{OUT2}$ ,  $V_{OUT3}$ ,  $V_{OUT4}$ , and  $V_{OUT5}$ . Graph each of these outputs with respect to time. The more detailed your graphs are, the more points you get (up to 6 points per graph).



$V_{OUT3}$  and  $V_{OUT4}$  may look different depending on initial phase when circuit started operation. Assuming 0 phase,



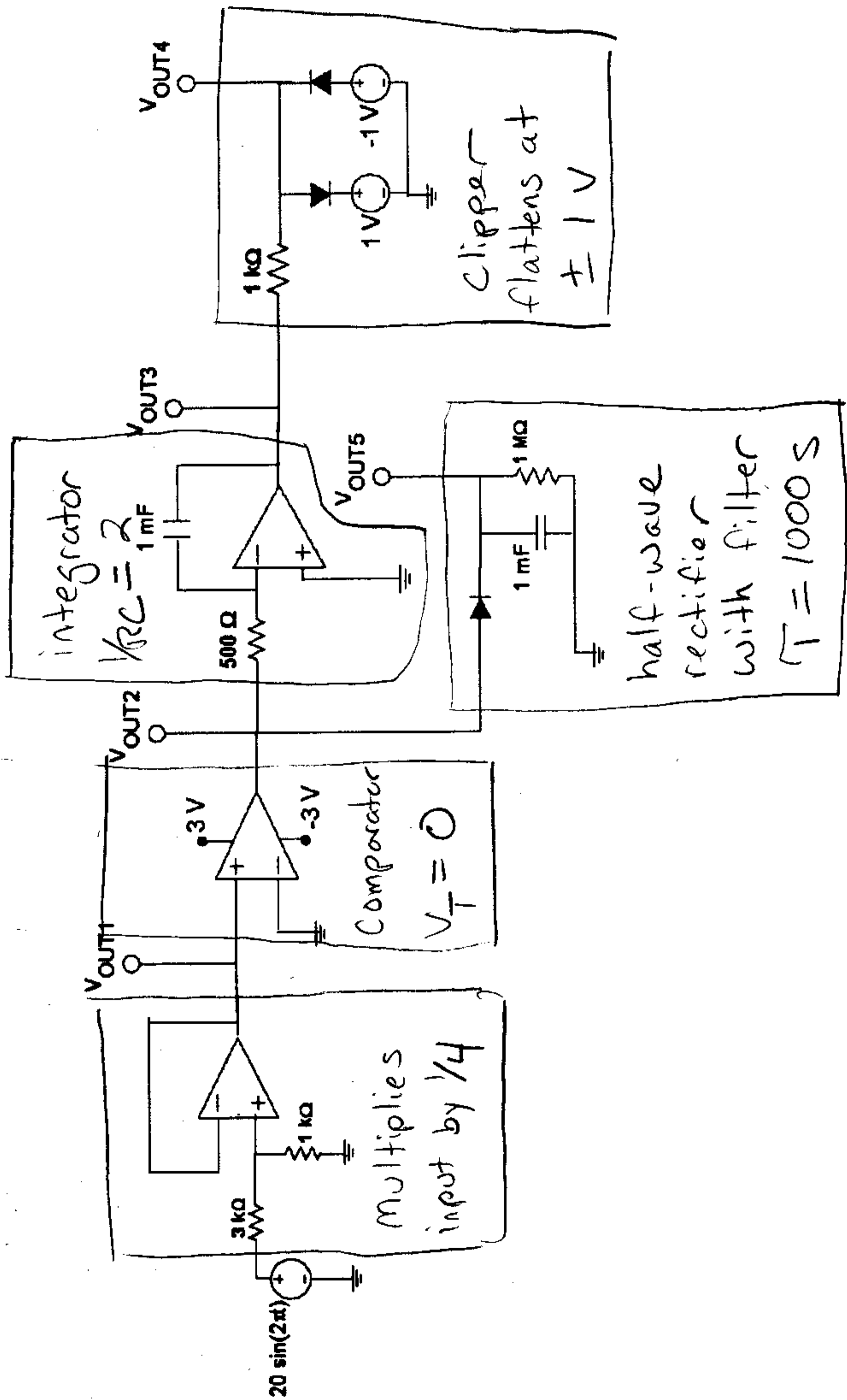
$V_{OUT5}$  assuming small-signal diode



- Charging is almost immediate since diode resistance small
- Discharging extremely slow, keeps 99.95% of value after 0.5s

Name: Solutions

Problem 6 continued



**Problem 7: 60 Points Possible**

Perform 2 of the following 3 designs, worth 30 points each. If you complete all 3 designs, the 2 highest scores will be counted.

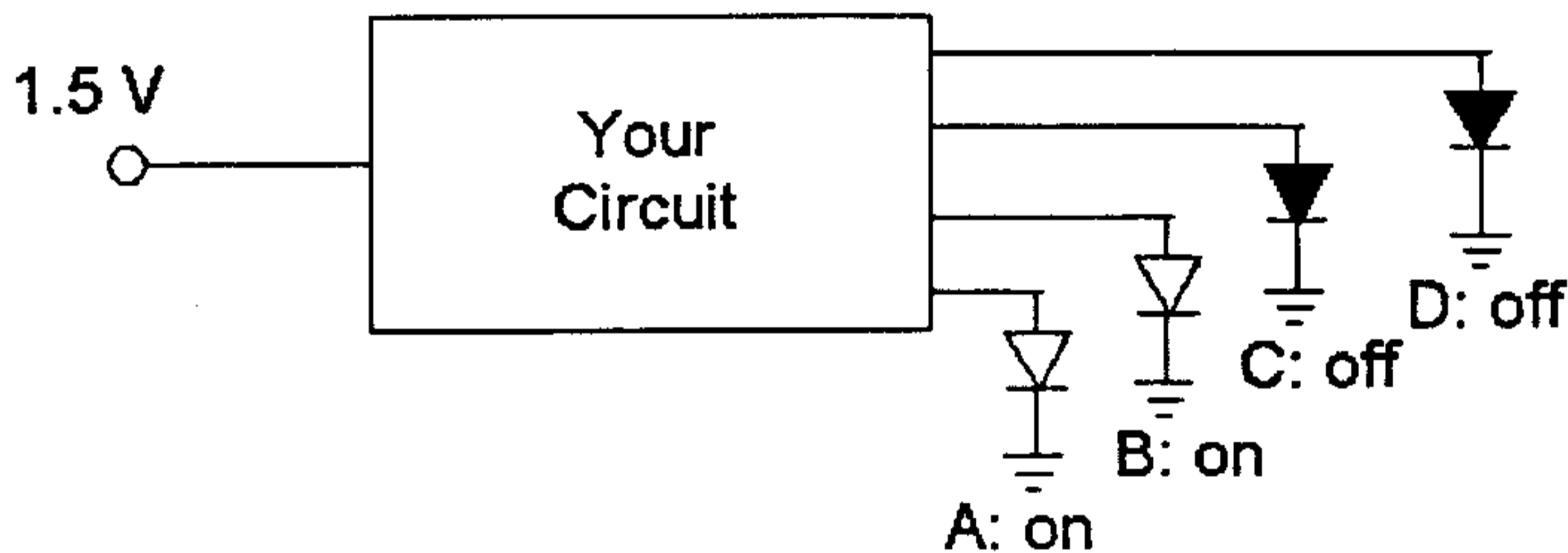
Indicate clearly which design problem you are answering, and what your final design is. Indicating the important features of your design will help us give you maximum credit.

- a) As input, you are given an analog voltage (continuous voltage) between 0 V and 4 V. You are also given 4 LED's named A, B, C and D.

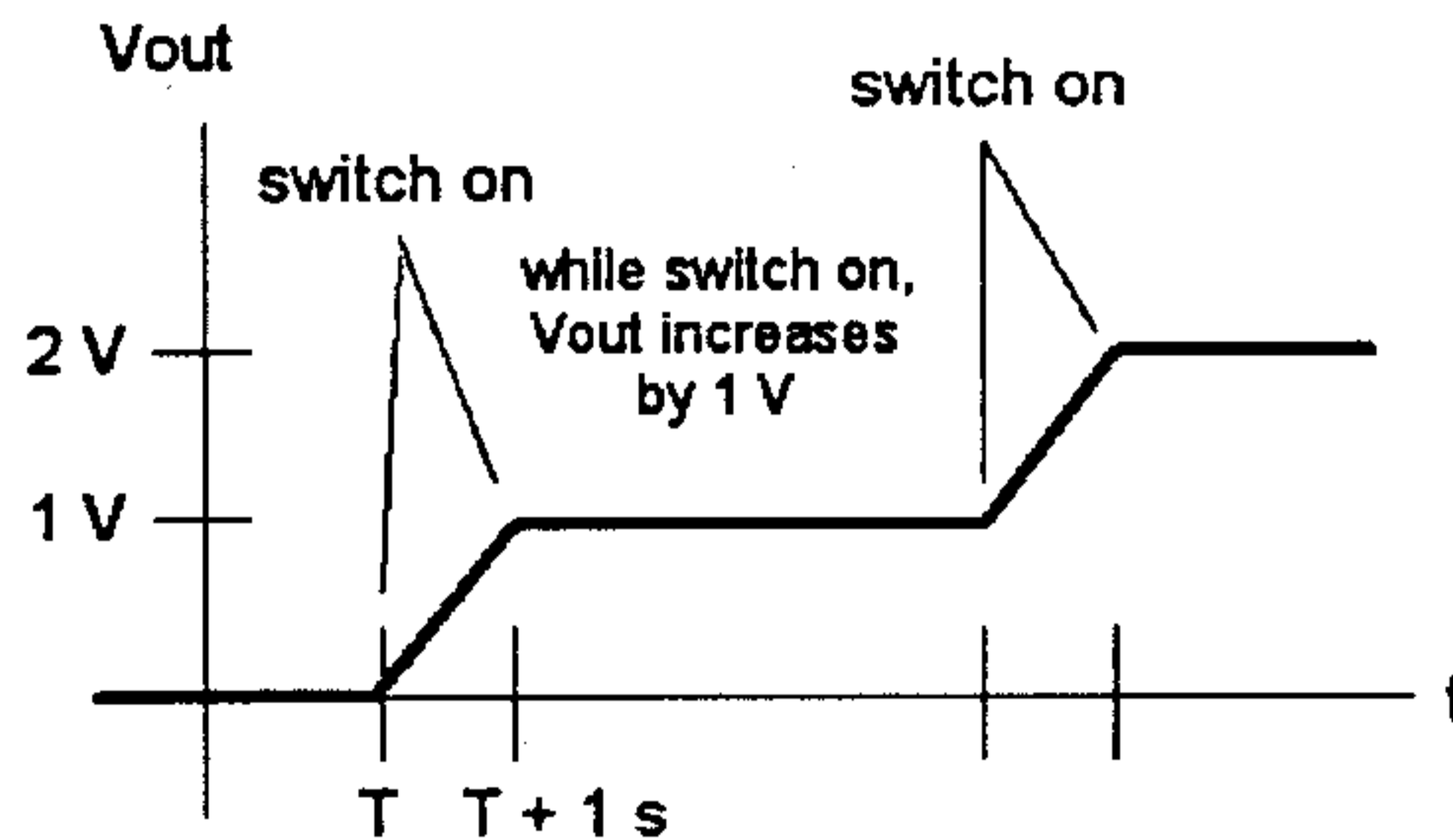
If the input voltage is below 1 V, LED A should light up. If input is between 1 V and 2 V, LED's A and B light up. If input is between 2 V and 3 V, LED's A, B and C light up. If input is above 3 V, LED's A, B, C, and D light up.

Example:

$V_{in} = 1.5 V$ , so LED's A and B light up:



- b) A user will occasionally flip a switch on, leave it on for 1 second and then turn it off. Create a circuit that counts how many times the user has done this. The output should look like this:



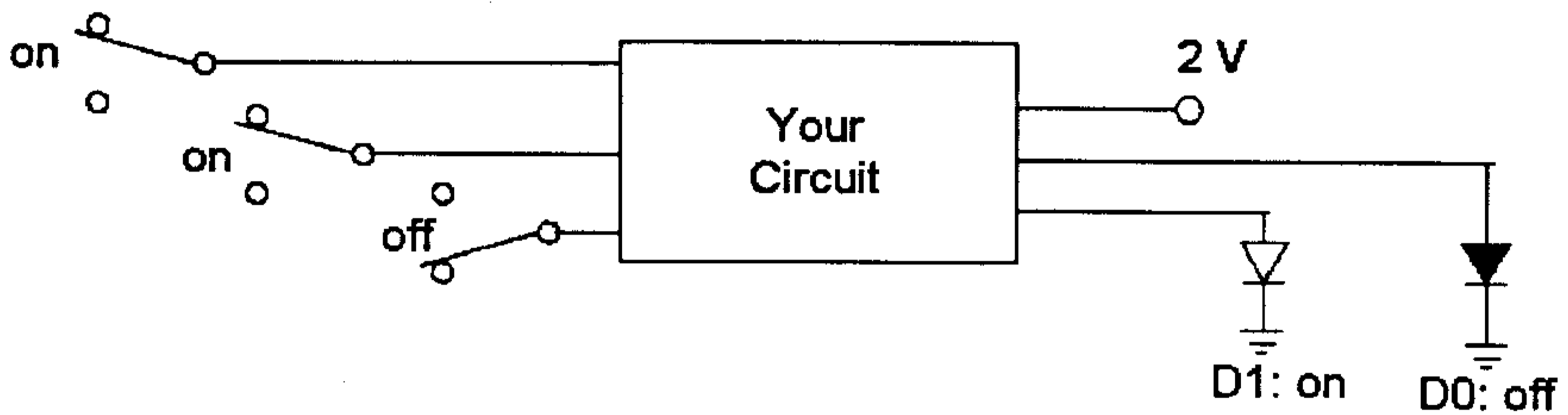
Include a way to reset the counter in your design, that is, a way to take the output back to zero at the flip of a switch. You may use push-button or regular switches.

c) You are given 3 ordinary switches which can be in the "on" position or the "off" position. Create a circuit that counts the number of switches that are "on" and provides output:

- 1) in binary (LED's that represent the binary number of "on" switches)
- 2) and as an analog voltage (output 0 V for 0 switches on, 1 V for 1 switch on, 2 V for 2 switches on, 3 V for 3 switches on).

Example:

2 switches turned on, so binary output is 10 and analog output is 2 V:

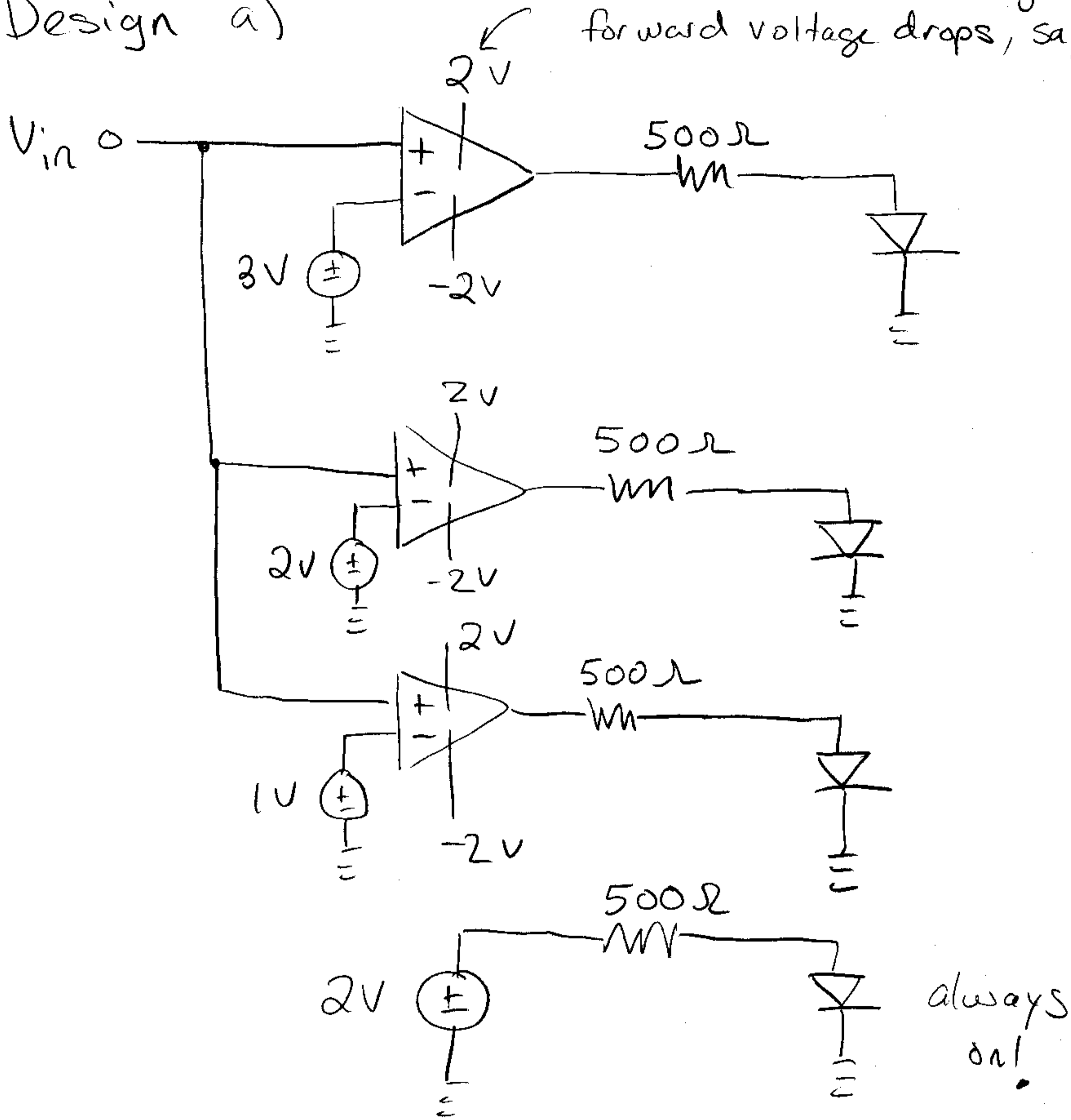


(You would have to attach something to the on/off terminals on each switch to make this work, that is not shown here for simplicity).

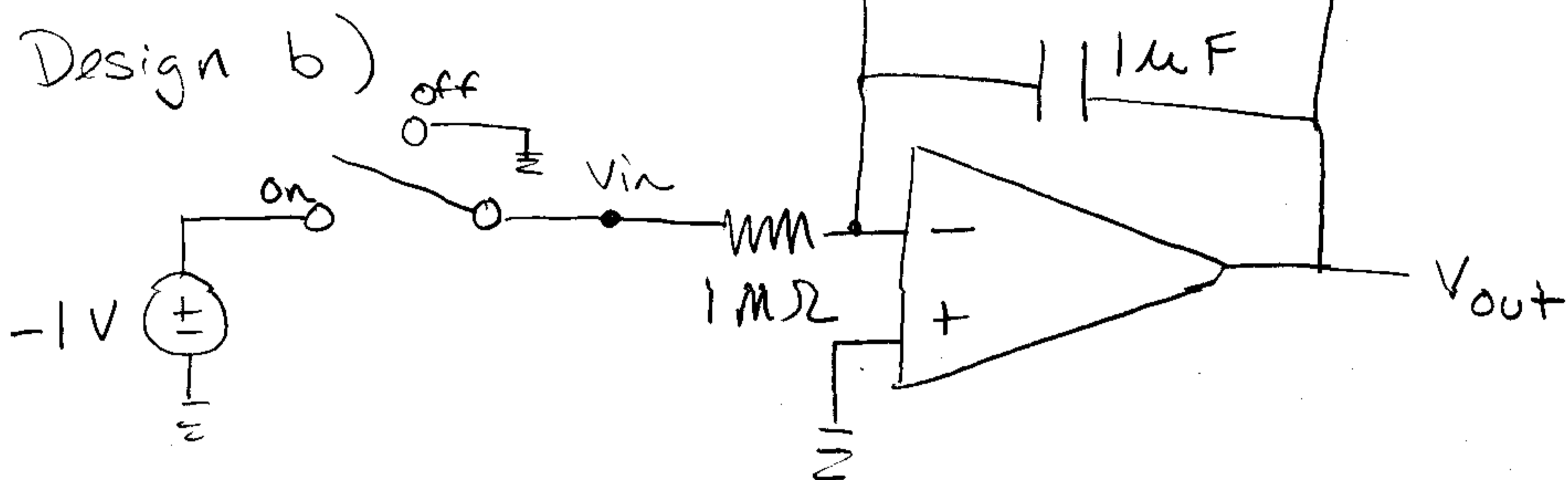
Problem 7 Workspace

Design a)

Sometimes LED's have higher forward voltage drops, say  $\approx 1V$ .



This is just one of many possible designs.

Problem 7 Workspace

On the integrator,

$$V_{out} = -\frac{1}{RC} \int_0^t V_{in}(t') dt'$$

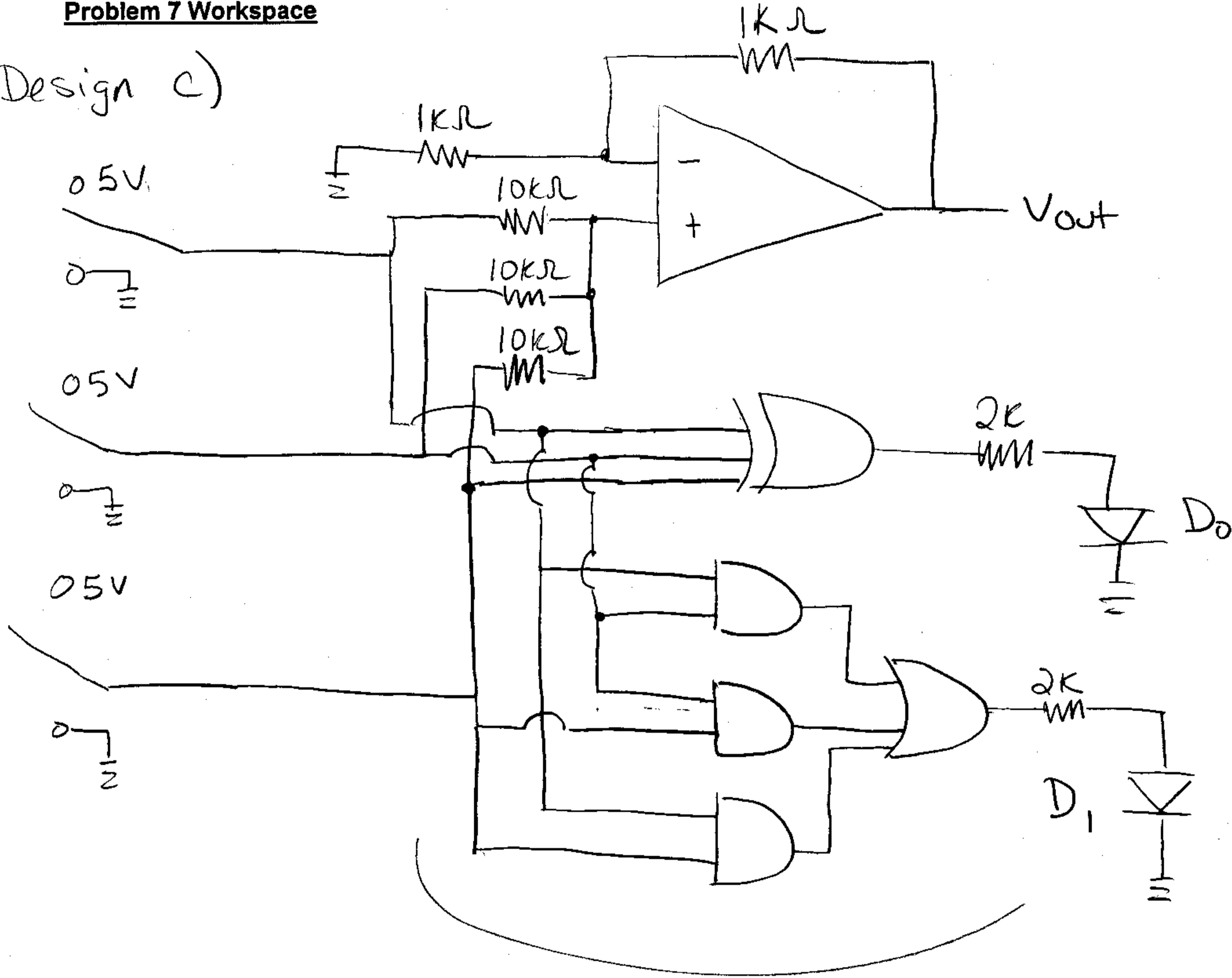
So making  $RC = 1s$  accomplishes our needs.

Note:

- When resetting circuit, make  $V_{in} = 0V$ . You could attach an override switch that makes  $V_{in} = 0V$  when reset switch down.
- Try to choose small capacitance to make reset time constant small. If you do this with small reset resistance, current will be high.
- Operation continues normally until  $V_{out}$  hits a rail. Make the rail your max counter value.

Problem 7 Workspace

Design c)



3-bit adder

You should avoid using logic voltages below 3V unless you have special technology.